CY2545C022, CY2545C022T

Last Updated: 07/29/2010

Bill of Materials	Assembly site A
Mold compound	G700
Lead frame/Substrate	STW C194/AQT C194/LG Micron C194
Lead finish/Solder ball	Amkor Pure Sn
Die attach	8290
Bonding wire	Heraeus/MKE/Heesung
Die	Fab site A

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